

PACKAGE STRUCTURE AND METHOD FOR MANUFACTURING SAME, SEMICONDUCTOR DEVICE

ABSTRACT

Embodiments of the invention provide a package structure, a method for manufacturing the same and a semiconductor device. The package structure includes N first pads, N redistribution layers, second pads and third pads. Each of the N first pads is formed by an interconnect layer exposed by one of the via holes. Each of the N redistribution layers covers the isolation layer and is electrically connected with a corresponding one of the N first pads. Some first pads are arranged side by side along a first direction near a first edge of the semiconductor functional structure, and other first pads are arranged side by side along the first direction near a second edge of the semiconductor functional structure. The exposed parts of each of the redistribution layers form a second pad and a third pad. Both an offset direction and an offset distance between a center point of the second pad and a center point of a corresponding first pad are same for all the second pad. A relative position between the second pad and the third pad for some redistribution layers is different from a relative position between the second pad and the third pad for other redistribution layers.

[Fig. 5]